Receiving Means for Mounting of Wafers

Abstract

This invention relates to a receiving means for receiving and mounting of wafers with the following features:

- a mounting surface (1o),

- mounting means for mounting of the wafer on the mounting surface (1o) and

- compensation means (3, 4, 5, 6) for active, especially locally controllable, at least partial compensation of local and/or global distortions of the wafer.

Furthermore this invention relates to a device and a method for alignment of a first wafer with a second wafer using an aforementioned receiving means.

Figure 3b